

• General Description

The AGM13T30D combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{\text{DS(ON)}}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low R_{DS(ON)} to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

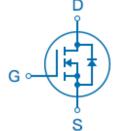
Product Summary

BVDSS	RDSON	ID
135V	32.5mΩ	30A

TO-252 Pin Configuration







Top View

Bottom View

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM13T30D	AGM13T30D	TO-252	330mm	16mm	2500

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	135	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) (Note 1)	30	Α
_	Drain Current-Continuous(Tc=100℃)	20	Α
IDM (pluse)	Drain Current-Pulsed (Note 2)	120	Α
PD	Maximum Power Dissipation(Tc=25℃)	120	w
	Maximum Power Dissipation(Tc=100℃)	60	w
EAS	Avalanche energy (Note 3)	21	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 175	$^{\circ}$

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹		50	°C/W
RθJC	Thermal Resistance Junction-Case ¹		1.25	°C/W



Table 3. Electrical Characteristics (TJ=25 ℃ unless otherwise noted)

able 3.	Electrical Characteristics (TJ=25℃unl	ess otherwise noted)				
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off Sta	ates					
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	135	147		V
IDSS	Zero Gate Voltage Drain Current	VDS=135V,VGS=0V			1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	2	2.8	4	V
gFS	Forward Transconductance	VDS=5V,ID=5A		11		S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=10A		32.5	38	mΩ
Dynamic (Characteristics					
Ciss	Input Capacitance	VDS=40V,VGS=0V,		622		pF
Coss	Output Capacitance	F=1MHZ		251		pF
Crss	Reverse Transfer Capacitance			11		pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz		3.5		Ω
Switching	Times					
td(on)	Turn-on Delay Time			10		nS
tr	Turn-on Rise Time	VGS=10V,VDS=75V,		6.5		nS
td(off)	Turn-Off Delay Time	RGEN=3 Ω , RL=7.5 Ω		16		nS
tf	Turn-Off Fall Time			7.0		nS
Qg	Total Gate Charge			33		nC
Qgs	Gate-Source Charge	VGS=10V, VDS=75V, ID=20A		7.2		nC
Qgd	Gate-Drain Charge	ID-20A		7.2		nC
Source-Di	rain Diode Characteristics					
ISD	Source-Drain Current(Body Diode)				30	А
VSD	Forward on Voltage	VGS=0V,IS=20A			1.2	V
trr	Reverse Recovery Time	IF=20A , dI/dt=100A/μs ,		30		ns
Qrr	Reverse Recovery Charge	TJ=25℃		135		nc

Notes 1.The maximum current rating is package limited.

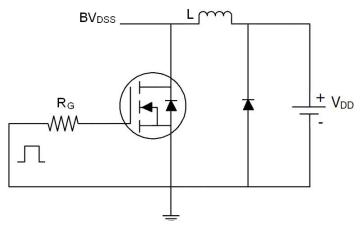
Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25 $^{\circ}\text{C}$,VDD=50V,Vgs=10V,L=0.1mH,RG=25ohm

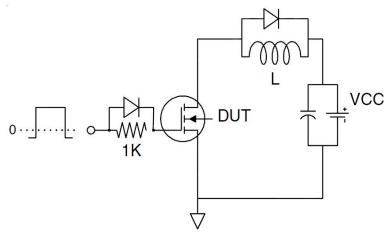


Test Circuit

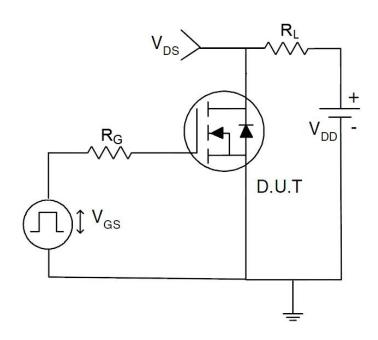
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics

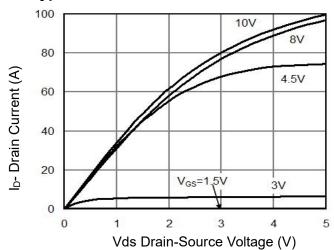


Figure 1 Output Characteristics

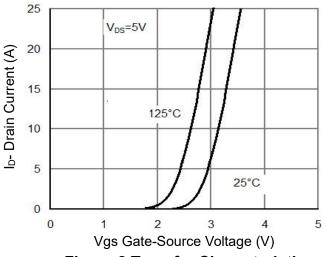


Figure 2 Transfer Characteristics

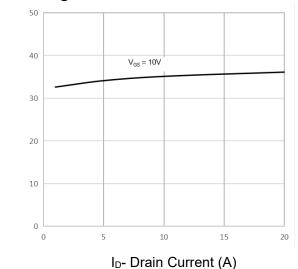


Figure 3 Rdson- Drain Current

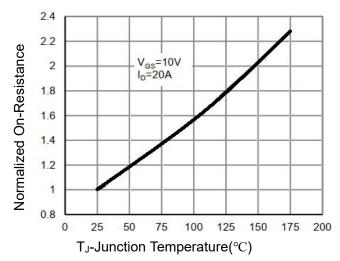


Figure 4 Rdson-Junction Temperature

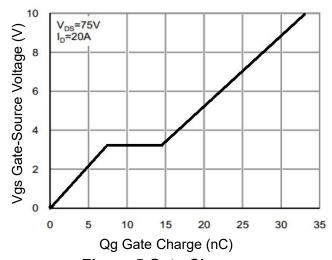


Figure 5 Gate Charge

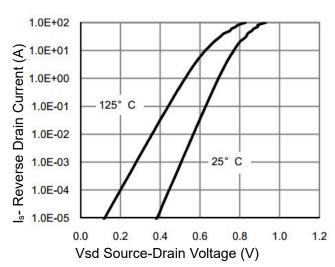


Figure 6 Source- Drain Diode Forward



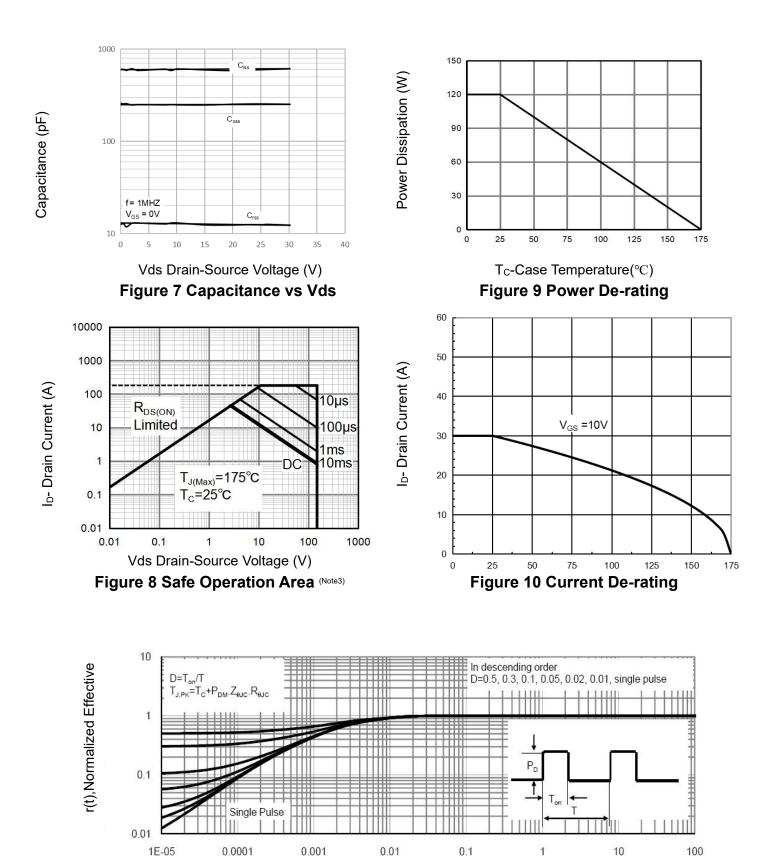
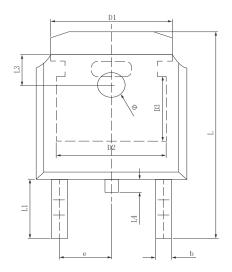


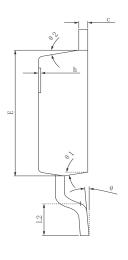
Figure 11 Normalized Maximum Transient Thermal Impedance

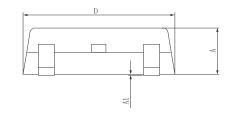
Square Wave Pluse Duration(sec)

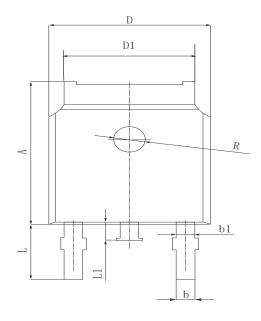


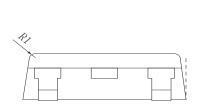
•Dimensions (TO-252)

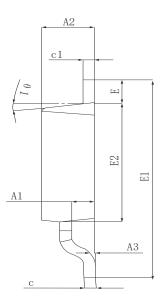


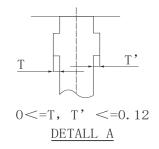






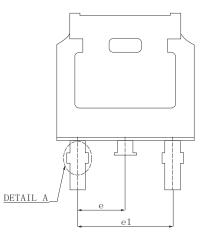






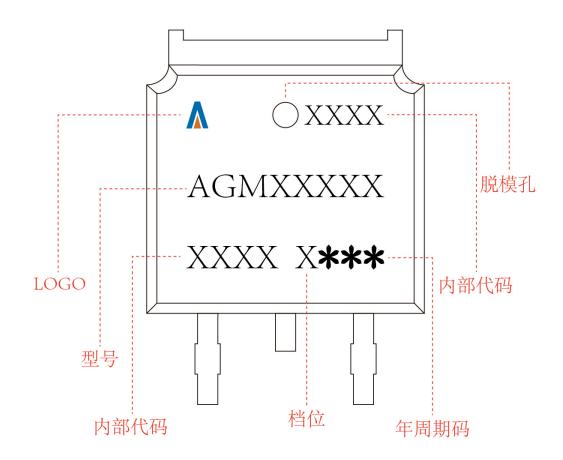
	MILLIMETER			
SYMBOL	MIN	Typ.	MAX	
A	2. 200	2. 300	2.400	
A1	0.000		0.127	
b	0.640	0.690	0.740	
c(电镀后)	0.460	0.520	0.580	
D	6.500	6.600	6. 700	
D1		5.334 REF		
D2	4.826 REF			
D3	3.166 REF			
Е	6.000	6. 100	6. 200	
е		2.286 TYP		
h	0.000	0.100	0.200	
L	9.900	10.100	10.300	
L1	2.888 REF			
L2	1.400	1.550	1.700	
L3	1.600 REF			
L4	0.600	0.800	1.000	
Φ	1.100	1.200	1.300	
θ	0°		8°	
θ 1	9° TYP			
θ2		9° TYP		

SYMBOL	MILLIMETER			
	MIN	NOM	MAX	
A	7.050	7. 100	7. 150	
A1	0.960	1.010	1.060	
A2	2. 250	2.300	2.350	
A3	0.000	0.050	0.100	
b		0.760REF.		
b1		1.000REF.		
С	0. 508REF.			
c1	0. 508REF.			
D	6. 550	6.600	6.650	
D1	5. 220	5. 320	5. 420	
Е	0.950	1.000	1.050	
E1	9.700	9. 900	10. 100	
E2	6.050	6. 100	6.150	
е	2. 286BSC			
e1	4. 572REF.			
L	2.650	2.800	2.950	
L1	0.700	0.800	0.900	
θ 1	7° REF.			
R	1.300REF.			
R1	0.250REF.			





TO-252 Marking Instructions:





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